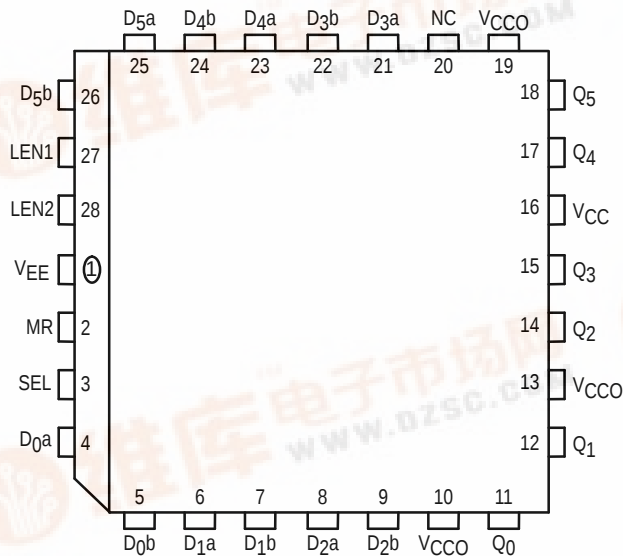


6-Bit 2:1 Mux-Latch

The MC10E/100E155 contains six 2:1 multiplexers followed by transparent latches with single-ended outputs. When both Latch Enables (LEN1, LEN2) are LOW, the latch is transparent, and output data is controlled by the multiplexer select control, SEL. A logic HIGH on either LEN1 or LEN2 (or both) latches the outputs. The Master Reset (MR) overrides all other controls to set the Q outputs LOW.

- 850ps Max. LEN to Output
- 825ps Max. D to Output
- Single-Ended Outputs
- Asynchronous Master Reset
- Dual Latch-Enables
- Extended 100E V_{EE} Range of $-4.2V$ to $-5.46V$
- 75k Ω Input Pulldown Resistors

Pinout: 28-Lead PLCC (Top View)



* All V_{CC} and V_{CCO} pins are tied together on the die.

PIN NAMES

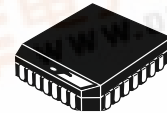
Pin	Function
D0a – D04	Input Data a
D0b – D4b	Input Data b
SEL	Data Select Input
LEN1, LEN2	Latch Enables
MR	Master Reset
Q0 – Q4	Outputs

TRUTH TABLE

SEL	Data
H	a
L	b

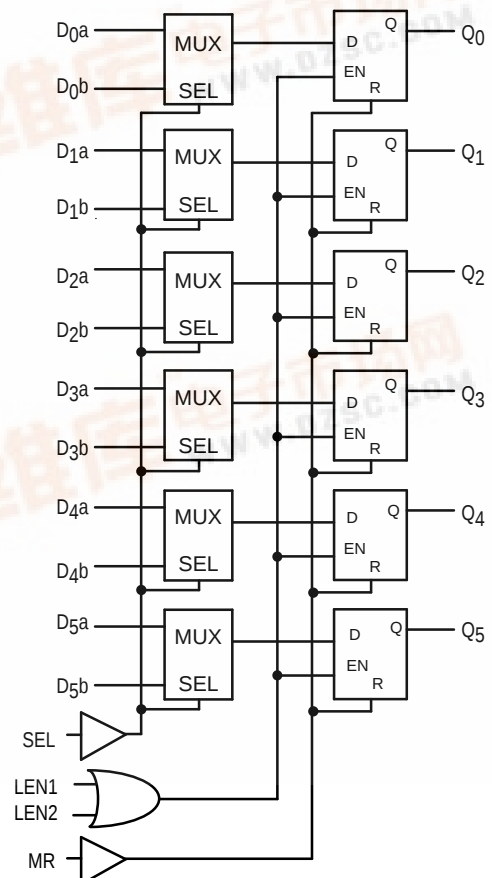
MC10E155 MC100E155

6-BIT 2:1 MUX-LATCH



FN SUFFIX
PLASTIC PACKAGE
CASE 776-02

LOGIC DIAGRAM



MC10E155 MC100E155

DC CHARACTERISTICS ($V_{EE} = V_{EE(min)}$ to $V_{EE(max)}$; $V_{CC} = V_{CCO} = GND$)

Symbol	Characteristic	0°C			25°C			85°C			Unit	Condition
		min	typ	max	min	typ	max	min	typ	max		
I_{IH}	Input HIGH Current			150			150			150	μA	
I_{EE}	Power Supply Current										mA	
	10E		85	102		85	102		85	102		
	100E		85	102		85	102		98	117		

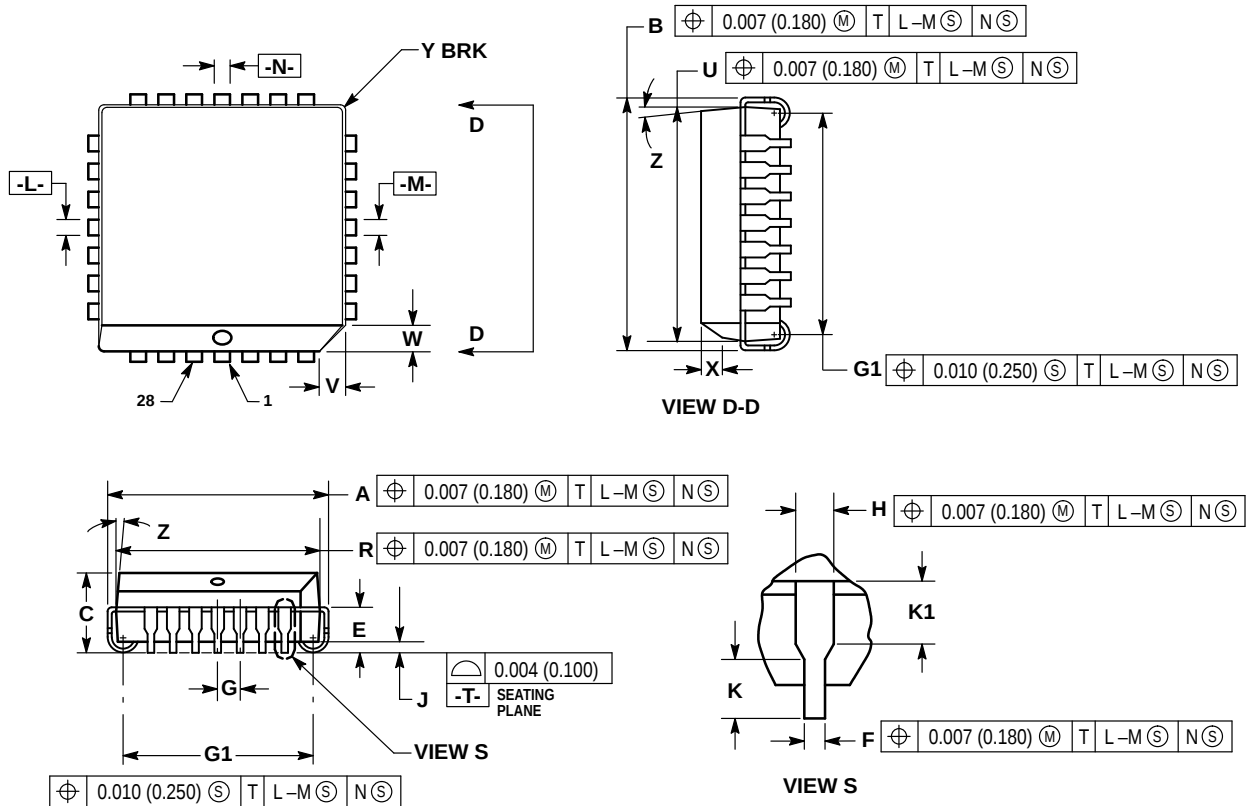
AC CHARACTERISTICS ($V_{EE} = V_{EE(min)}$ to $V_{EE(max)}$; $V_{CC} = V_{CCO} = GND$)

Symbol	Characteristic	0°C			25°C			85°C			Unit	Condition
		min	typ	max	min	typ	max	min	typ	max		
t_{PLH} t_{PHL}	Propagation Delay to Output D SEL LEN MR	325 475 350 450	500 675 500 600	700 925 750 850	325 475 350 450	500 675 500 600	700 925 750 850	325 475 350 450	500 675 500 600	700 925 750 850	ps	
t_S	Setup Time D SEL	300 500	100 250		300 500	100 250		300 500	100 250			
t_H	Hold Time D SEL	300 0	-100 -250		300 0	-100 -250		300 0	-100 -250			
t_{RR}	Reset Recovery Time	800	650		800	650		800	650		ps	
t_{PW}	Minimum Pulse Width MR	400			400			400			ps	
t_{SKEW}	Within-Device Skew		75			75			75		ps	1
t_r t_f	Rise/Fall Times 20 - 80%	300	450	800	300	450	800	300	450	800	ps	

1. Within-device skew is defined as identical transitions on similar paths through a device.

OUTLINE DIMENSIONS

FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 776-02
ISSUE D



NOTES:

- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- DIM G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIM R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	—	1.02	—

MC10E155 MC100E155

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